AZ® 50XT Photoresist

Thick Positive Novolak Photoresist
For Plating & Etch Applications

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AZ® 50XT Photoresist

- Positive resist for developing plating and wafer bumping applications
- 50 to 80 micron single coat capability. Up to 120µm FT double coat capability
- 3 to 1 aspect ratio. Excellent sidewall profiles. Wide process latitude
- Inorganic developer recommended
- Compatible with existing thick film processes

Copper studs
AZ® 50XT at 75µm Film Thickness

Solder studs (SnPb)
AZ® 50XT at 75µm Film Thickness
AZ®, 50XT Spectral Response Curve

Index of Refraction ‘n’

Extinction Coefficient ‘k’

Wavelength
AZ® 50XT on Copper
Expose on Ultratech-Saturn, 75µm FT, 100µm CH,
AZ® 50XT on Cu – Plating Performance
Expose on Ultratech-Saturn, 75µm FT, 100µm CH,

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Post Copper Plating and Strip

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AZ® 50XT Photoresist

Exposure Latitude on Si, 20µm Contact Holes, FT = 25µm

2100 mJ/cm²
2200 mJ/cm²
2300 mJ/cm²
2400 mJ/cm²

2500 mJ/cm²
2600 mJ/cm²
2700 mJ/cm²
2800 mJ/cm²
AZ® 50XT Photoresist
Copper Plating - ~20µm High Bumps

CD = 20µm

CD = 30µm

CD = 50µm